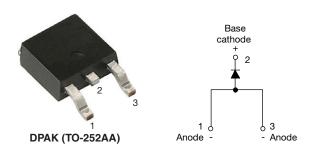


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# High Voltage Surface Mountable Input Rectifier Diode, 8 A



PRIMARY CHARACTERISTICS					
I <sub>F(AV)</sub>	8 A				
V <sub>R</sub>	1200 V				
V <sub>F</sub> at I <sub>F</sub>	1.1 V				
I <sub>FSM</sub>	150 A				
T <sub>J</sub> max.	150 °C				
Package	DPAK (TO-252AA)				
Circuit configuration	Single				

#### **FEATURES**

- Glass passivated pellet chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C



- AEC-Q101 qualified
- Meets JESD 201 class 2 whisker test
- Flexible solution for reliable AC power rectification
- High surge, low V<sub>F</sub> rugged blocking diode for DC charging stations
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### **APPLICATIONS**

- On-board and off-board EV / HEV battery chargers
- · Renewable energy inverters

### **DESCRIPTION**

The VS-8EWS12SLHM3 rectifier high voltage series has been optimized for very low forward voltage drop, with moderate leakage.

The **high reverse voltage** range available allows design of input stage primary rectification with **outstanding voltage surge** capability.

OUTPUT CURRENT IN TYPICAL APPLICATIONS							
APPLICATIONS SINGLE-PHASE BRIDGE THREE-PHASE BRIDGE UNITS							
NEMA FR-4 or G10 glass fabric-based epoxy with 4 oz. (140 μm) copper	1.2	1.6					
Aluminum IMS, R <sub>thCA</sub> = 15 °C/W	2.5	2.8	A				
Aluminum IMS with heatsink, R <sub>thCA</sub> = 5 °C/W	5.5	6.5					

### Note

•  $T_A = 55 \,^{\circ}\text{C}$ ,  $T_J = 125 \,^{\circ}\text{C}$ , footprint 300 mm<sup>2</sup>

MAJOR RATINGS AND CHARACTERISTICS								
SYMBOL	MBOL CHARACTERISTICS VALUES UNITS							
I <sub>F(AV)</sub>	Sinusoidal waveform	8	Α					
V <sub>RRM</sub>		1200	V					
I <sub>FSM</sub>		150	Α					
V <sub>F</sub>	8 A, T <sub>J</sub> = 25 °C	1.10	V					
$T_J$		-55 to +150	°C					

VOLTAGE RATINGS							
PART NUMBER	V <sub>RRM</sub> , MAXIMUM PEAK REVERSE VOLTAGE V	V <sub>RSM</sub> , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I <sub>RRM</sub> AT 150 °C mA				
VS-8EWS12SLHM3	1200	1300	0.50				



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ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS		
Maximum average forward current	I <sub>F(AV)</sub>	T <sub>C</sub> = 105 °C, 180° conduction half sine wave	8			
Maximum peak one cycle	1	10 ms sine pulse, rated V <sub>RRM</sub> applied	125	А		
non-repetitive surge current	I <sub>FSM</sub>	10 ms sine pulse, no voltage reapplied	150			
Maximum I <sup>2</sup> t for fusing	l <sup>2</sup> t	10 ms sine pulse, rated V <sub>RRM</sub> applied	78	A <sup>2</sup> s		
Maximum I-t for fusing	1-1	10 ms sine pulse, no voltage reapplied	110	A-S		
Maximum I <sup>2</sup> √t for fusing	I <sup>2</sup> √t	t = 0.1 ms to 10 ms, no voltage reapplied	1100	A²√s		

ELECTRICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CO	VALUES	UNITS		
Maximum forward voltage drop	$V_{FM}$	8 A, T <sub>J</sub> = 25 °C		1.1	V	
Forward slope resistance	r <sub>t</sub>	T <sub>.1</sub> = 150 °C		20	mΩ	
Threshold voltage	V <sub>F(TO)</sub>	1j = 150 C		0.82	V	
Maximum rayaraa laakaga aurrant		T <sub>J</sub> = 25 °C	\/ _ rated \/	0.05	mA	
Maximum reverse leakage current	IRM	T <sub>J</sub> = 150 °C	$V_R$ = rated $V_{RRM}$	0.50	IIIA	

THERMAL - MECHANICAI PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T <sub>J</sub> , T <sub>Stg</sub>		-55 to +150	°C
Maximum thermal resistance, junction to case	R <sub>thJC</sub>	DC operation	2.5	°C/W
Typical thermal resistance, junction to ambient (PCB mount)	R <sub>thJA</sub> <sup>(1)</sup>		62	°C/VV
A managina at a susiant			1	g
Approximate weight			0.03	OZ.
Marking device		Case style DPAK (TO-252AA)	8EWS	12SH

#### Note

 $<sup>^{(1)}</sup>$  When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140  $\mu$ m) copper 40 °C/W

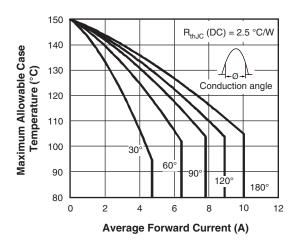


Fig. 1 - Current Rating Characteristics

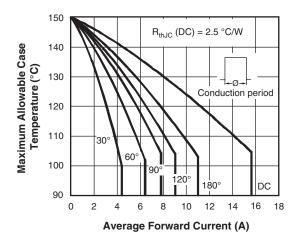


Fig. 2 - Current Rating Characteristics

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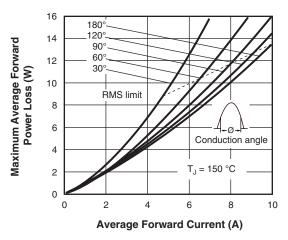


Fig. 3 - Forward Power Loss Characteristics

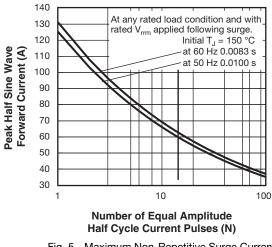


Fig. 5 - Maximum Non-Repetitive Surge Current

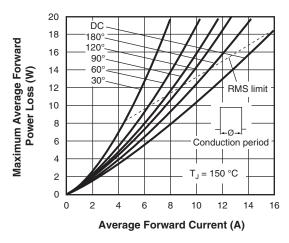


Fig. 4 - Forward Power Loss Characteristics

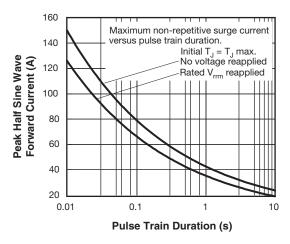


Fig. 6 - Maximum Non-Repetitive Surge Current

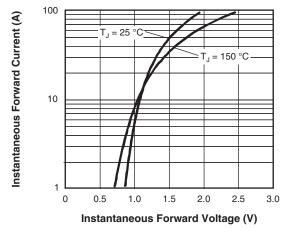


Fig. 7 - Forward Voltage Drop Characteristics

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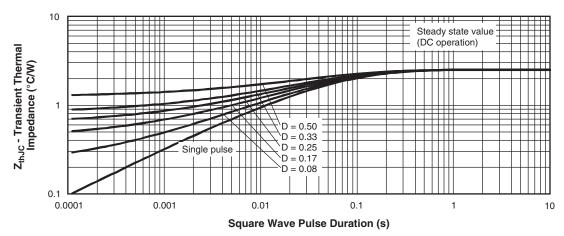


Fig. 8 - Thermal Impedance Z<sub>thJC</sub> Characteristics

### **ORDERING INFORMATION TABLE**

Device code	VS-	8	Е	w	s	12	S	L	Н	М3
	L									
	$\begin{pmatrix} 1 \end{pmatrix}$	(2)	(3)	(4)	(5)	( <del>6</del> )	(7)	(8)	9	(10)
	1	- Vis	hay Sen	nicondu	ctors pro	oduct				
	2	- Cu	rrent rati	ing (8 =	8 A)					
	3	- Cir	cuit conf	iguratio	n:					
	_	E =	single							
	4	- Pa	ckage:							
	_	W:	= DPAK	(TO-25	2AA)					
	5	- Typ	oe of sili	con:						
	_	S=	standa	rd recov	ery rect	ifier				
	6	- Vo	tage co	de x 100	) = V <sub>RRI</sub>	, ——	12 = 12	00 V		
	7		surface			_				
	8	- L=	tape an	ıd reel (I	eft orier	ited), fo	r differe	nt orien	tation c	ontact fa
	9		: AEC-Q	•		,,				
	10		vironme	•						

ORDERING INFORMATION (Example)						
PREFERRED P/N	PREFERRED P/N QUANTITY PER T/R MINIMUM ORDER QUANTITY PACKAGING DESCRIPTION					
VS-8EWS12SLHM3	3000	3000	13" diameter reel			

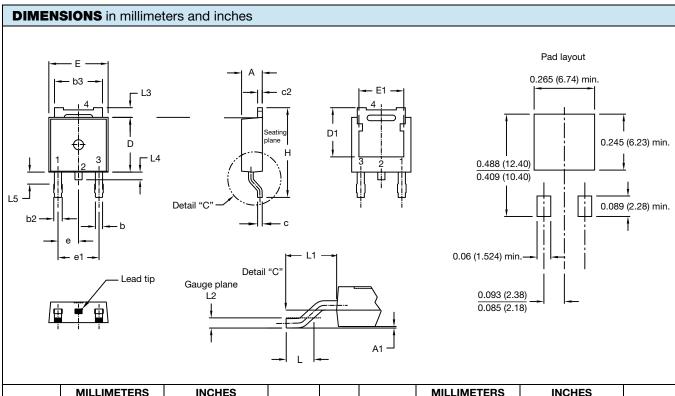
M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

LINKS TO RELATED DOCUMENTS					
Dimensions <u>www.vishay.com/doc?95519</u>					
Part marking information	www.vishay.com/doc?95518				
Packaging information	www.vishay.com/doc?96495				
SPICE model	www.vishay.com/doc?96668				



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# **DPAK (TO-252AA)**



SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STINIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	2.18	2.39	0.086	0.094	
A1	ı	0.13	-	0.005	
b	0.64	0.89	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	3
С	0.46	0.61	0.018	0.024	
c2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	5
D1	5.21	-	0.205	-	3
Е	6.35	6.73	0.250	0.265	5
E1	4.32	-	0.170	-	3

SYMBOL	MILLIN	IETERS	INCHES		NOTES
STIVIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
е	2.29	BSC	0.090	BSC	
Н	9.40	10.41	0.370	0.410	
L	1.40	1.78	0.055	0.070	
L1	2.74 BSC		0.108		
L2	0.51	BSC	0.020 BSC		
L3	0.89	1.27	0.035	0.050	3
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	2
	•	•			•

### Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension uncontrolled in L5
- (3) Dimension D1, E1, L3 and b3 establish a minimum mounting surface for thermal pad
- (4) Dimensions D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (5) Outline conforms to JEDEC® outline TO-252AA



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